# Radiative and Nonradiative Recombination

Ying Wan

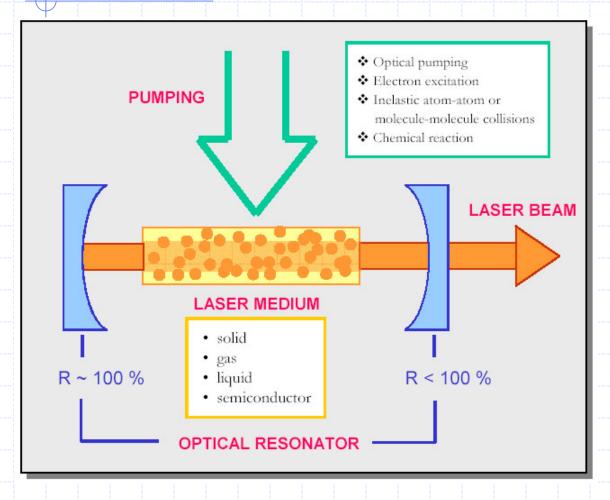
9/1/2003

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#### Contents

- Introduction to Laser Principle
- Radiative Recombination
- Nonradiative Recombination
- Threshold Current Density
- Leakage Current Density
- **♦** Temperature Dependence
- Reference

### Laser Principle



#### Requirement for Semiconductor Laser

- Gain Medium
  - Semiconductor material
- Optical Feedback
- Cleaved Facets (Fabry-Perot cavity)
- Mode Confinement
  - Dielectric Waveguiding
- Optical Gain
  - Electrical/optical pumping

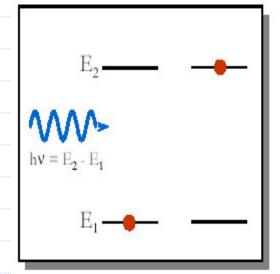
#### Definition of Recombination

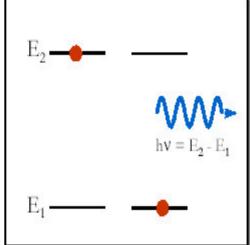
- A process whereby electrons and holes (carriers) are annihilated or destroyed.
- Reversed process is **Generation**: A process whereby electrons and holes are created.
- Classification:
  - A. Radiative Recombination: Photon
  - B. Nonradiative Recombination: Phonon or Lattice vibration

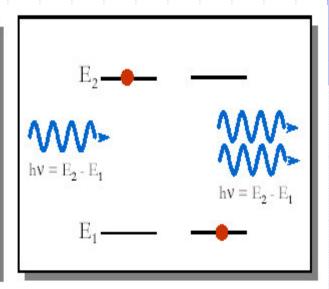
#### Radiative Recombination

- Radiative Recombination occurs when an electron in the conduction band recombines with a hole in the valence band and the excess energy is emitted in the form of a photon.
- Optical processes associated with radiative transitions are:
  - A. spontaneous emission
  - B. absorption or gain
  - C. stimulated emission

#### Radiative Transitions Processes







#### Absorption

✓ transition probability  $B_{12}$ 

#### Spontaneous emission

- √ transition probability A<sub>21</sub>
- √ random phase and direction

#### Stimulated emission

- √ transition probability B<sub>21</sub>
- has the same frequency and phase as the incident light
  - ⇒ light amplification

### **Important Terms**

#### Transparency

As pump rate increases, E<sub>fc</sub> increases and E<sub>fv</sub> decreases, the semiconductor becomes transparent at

$$E_{fc}$$
 -  $E_{fv}$  =  $E_g$ 

#### Optical gain

Difference between the stimulated emission and the absorption rate.

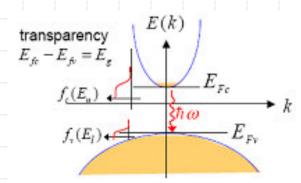
$$E_{fc}$$
 -  $E_{fv}$  >  $E_g$ 

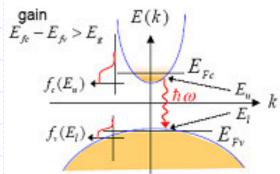
#### Threshold current (I<sub>th</sub>)

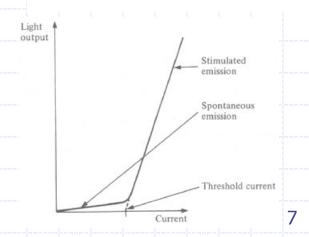
The lowest current at which stimulated emission exceeds spontaneous emission.

Below  $I_{\text{th}}$ , output mainly consists of spontaneous emission

Above  $I_{\text{th}}$ , stimulated emission begins to dominate







### Spontaneous Emission Rate

- Spontaneous emission rate increases when high enough (threshold) carrier density is injected into material to achieve optical gain.
- For every spontaneous photon emitted, A new carrier must be injected into the active region.
- Spontaneous emission contributes to threshold current, esp. in short-wavelength material.
- The total spontaneous emission rate per unit volume:

$$R(E) = \frac{4 \pi q^{2} \mu E}{m_{0}^{2} \varepsilon_{0} c^{3} h^{2}} \int_{-\infty}^{\infty} \rho_{c}(E') \rho_{c}(E'') f_{c}(E'') f_{v}(E'') |M_{if}|^{2} dE''$$
Where E'' = E' - E

### Radiative Current Density

Spontaneous emission rate can be approximated by

$$R = Bnp$$

where B: radiative recombination coefficient.

n and p: electron and hole density respectively.

The current density due to spontaneous emission alone:

$$J_r = qdR$$

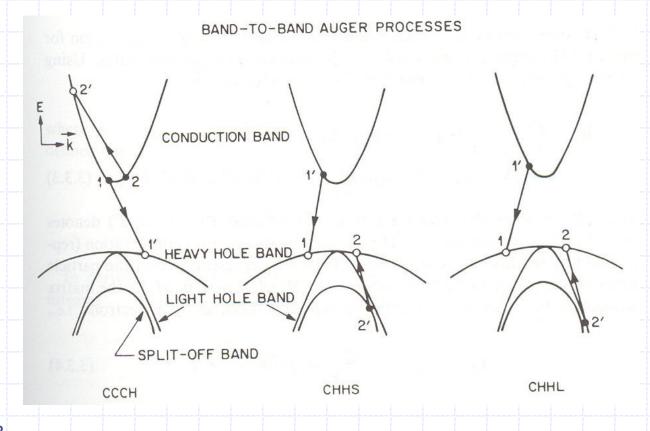
where d: active-layer thickness.

#### Nonradiative Recombination

- An electron in the conduction band recombines with a hole in the valence band and the excess energy is emitted in the form of heat in the semiconductor crystall lattice.
- Characterized by the absence of any useful emitted photons in the recombination process.
- Affecting performance of injection laser by increasing the threshold current
- Nonradiative Recombination processes include:
  - A. Auger Recombination
  - B. Surface Recombination
  - C. Recombination at defects

### **Auger Recombination**

- Generally the predominant nonradiative mechanism
- Involving 4 particle states (CCCH, CHHS, CHHL)



### **Auger Recombination Rate**

Representative values at room temperature:

 $C = 2 \sim 3 \times 10^{-29} \text{ cm}^6/\text{s} \text{ (bulk 1.3um InGaAsP)}$ 

 $C = 7 \sim 9 \times 10^{-29} \text{ cm}^6/\text{s} \text{ (bulk 1.55um InGaAsP)}$ 

 $C = 4 \sim 5 \times 10^{-30} \text{ cm}^6/\text{s} \text{ (bulk GaAs)}$ 

Auger Recombination rate is not well characterized for other material systems.

- Difficulty with Auger recombination:
  - A. Accurate information of the band structure at more than a bandgap away from the band edge must be known.
  - B. Overlap integrals of "k-space distant" Bloch functions must also be known.
- Theories are inevitably made very simplifying assumptions.

### Nonradiative Recombination Current Density

Auger Recombination rate (approximately)

$$R_a = Cn^{-3}$$

Where C: Auger coefficient

n: injected carrier density

**Defect and Surface Recombination rate**  $R_d = A_{nr} n$ 

Where  $A_{nr}$ : Trap and surface recombination coefficient

The current density due to Nonradiative Recombination :

$$J_{nr} = qd (R_a + R_d) = qd (Cn^3 + A_{nr} n)$$

### Threshold Current Density

Total threshold current density:

$$J_{th} = qd (A_{nr} n_{th} + Bn_{th}^{2} + Cn_{th}^{3}) + J_{L}$$

where n<sub>th</sub>: the injected carrier density at threshold

 $J_1$ : the leakage current density

For good quality laser, e.g. InGaAsP, the first term is negligible,

$$J_{th} \cong qd \left(Bn_{th}^2 + Cn_{th}^3\right) + J_L = J_r + J_{nr} + J_L$$
where
$$J_r = qd \left(Bn_{th}^2\right) = qdR$$

$$J_{nr} = qd (Cn_{th}^{3}) = qdR_{a}$$

#### Heterojunction Carrier Leakage

- Caused by diffusion and drift of electrons and holes from the edges of the active region to the cladding layers.
- Must be considered under high temperature or material systems which do not have the luxury of large heterobarriers.
- Calculation: find the minority carrier density spill over the active layer into the cladding layer interface, then find the diffusion and drift currents.

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### Leakage Current Density

#### Electron leakage current:

$$J_{n} = qD_{n}N_{p0}\left[\sqrt{\frac{1}{L_{n}^{2}} + \frac{1}{L_{nf}^{2}}} \coth \sqrt{\frac{1}{L_{n}^{2}} + \frac{1}{L_{nf}^{2}}} x_{p} + \frac{1}{L_{nf}}\right]$$

where D<sub>n</sub>: minority electron diffusion, coefficient

 $N_{p0}$ : electron population at the edge of p-cladding

L<sub>n</sub>: minority electron diffusion length

L<sub>nf</sub>: drift length

#### In quantum well laser, it can be approximated to:

$$J_L = qd \frac{N}{\tau_n}$$

where  $\mathcal{T}_n$ : minority carrier lifetime

d: active layer thickness

### Temperature Dependence of J<sub>th</sub>

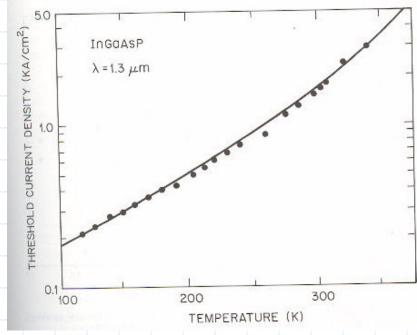
For double-heterostructure lasers:

$$I_{th}(T) = I_0 \exp(T/T_0)$$

where T0: characteristic temperature

## High temperature dependence of Jth of InGaAsP Laser

- Heterobarrier leakage
- Auger Recombination
- •Intervalence band absorption



Measured J<sub>th</sub> as a fun. Of temperature for a 1.3 um InGaAsP-InP laser

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9/1/2003